

ZX5T955Z.

140V PNP Low saturation medium power transistor in SOT89

Summary

$BV_{CEO} = -140V$; $R_{SAT} = 85m\Omega$; $I_C = -3A$

Description

Packaged in the SOT89 outline this new 5th generation low saturation 140V PNP transistor offers low on state losses making it ideal for use in DC-DC circuits, line switching and various driving and power management functions.

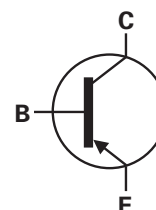


Features

- 3 amps continuous current
- Up to 10 amps peak current
- Very low saturation voltages

Applications

- Motor driving
- Line switching
- High side switches
- Subscriber line interface cards (SLIC)

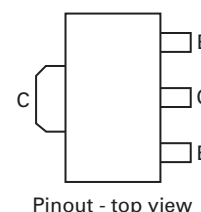


Ordering Information

Device	Reel Size	Tape Width	Quantity Per Reel
ZX5T955TA	7"	12mm	1000

Device Marking

955



Absolute maximum ratings

Parameter	Symbol	Limit	Unit
Collector-base voltage	BV_{CBO}	-180	V
Collector-emitter voltage	BV_{CEO}	-140	V
Emitter-base voltage	BV_{EBO}	-7	V
Continuous collector current ^(a)	I_C	-3	A
Peak pulse current	I_{CM}	-10	A
Power dissipation at $T_{amb}=25^{\circ}C^{(a)}$ Linear derating factor	P_D	1.5 12	W mW/°C
Power dissipation at $T_{amb}=25^{\circ}C^{(b)}$ Linear derating factor	P_D	2.1 16.8	W mW/°C
Operating and storage temperature range	T_j, T_{stg}	-55 to 150	°C

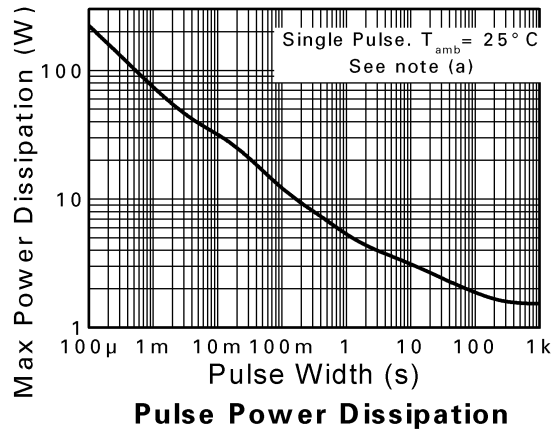
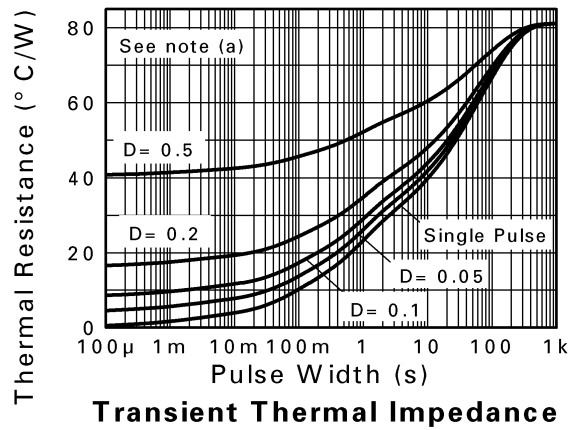
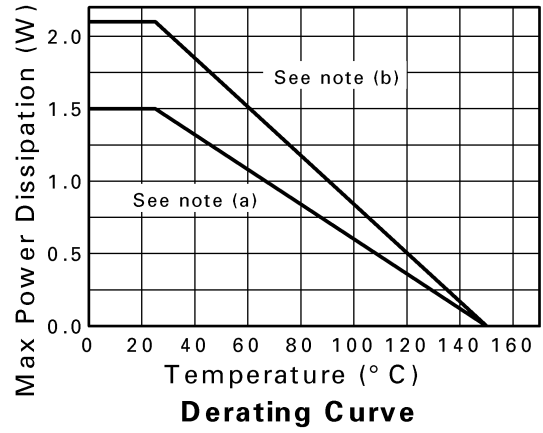
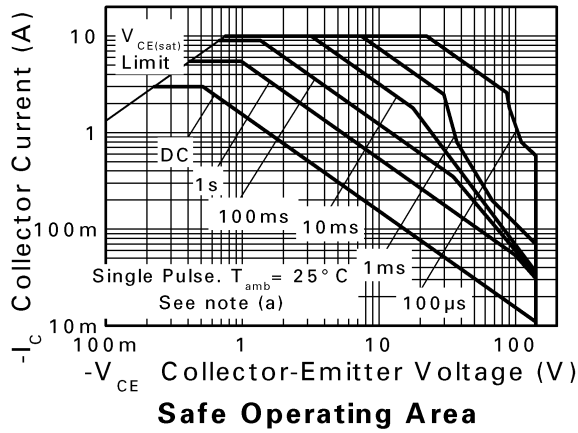
Thermal resistance

Parameter	Symbol	Limit	Unit
Junction to ambient ^(a)	$R_{\theta JA}$	83	°C/W
Junction to ambient ^(b)	$R_{\theta JA}$	60	°C/W

(a) For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

(b) For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

Characteristics

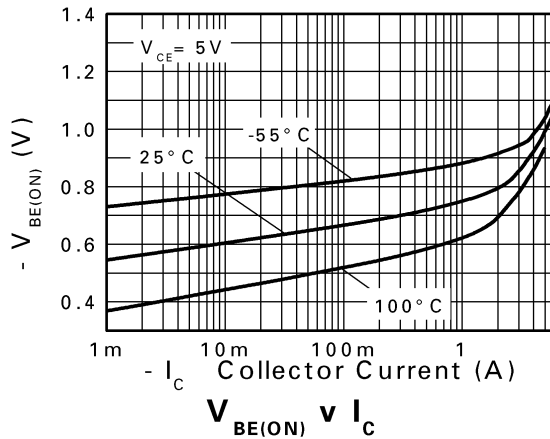
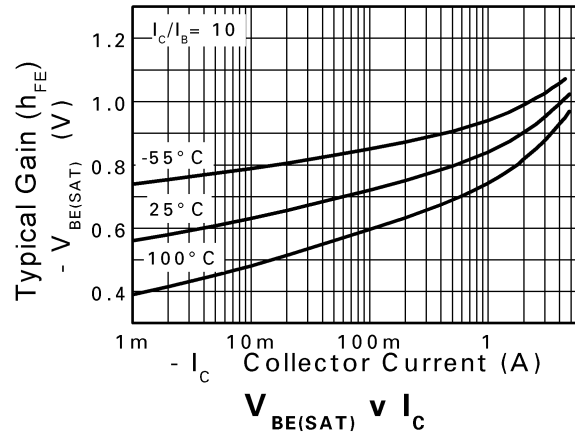
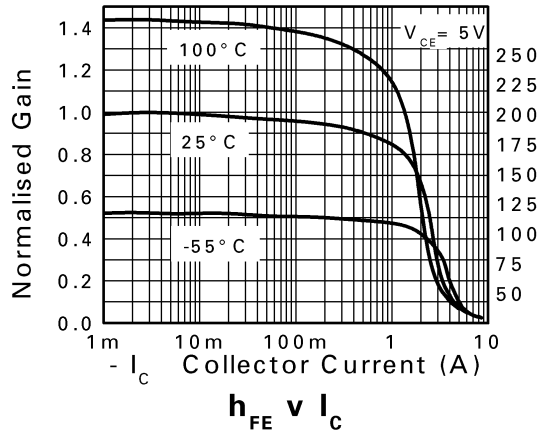
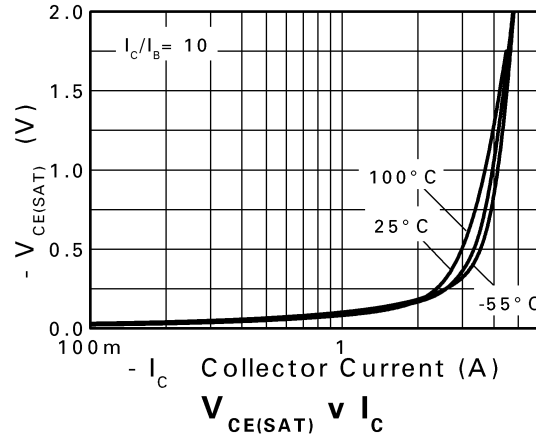
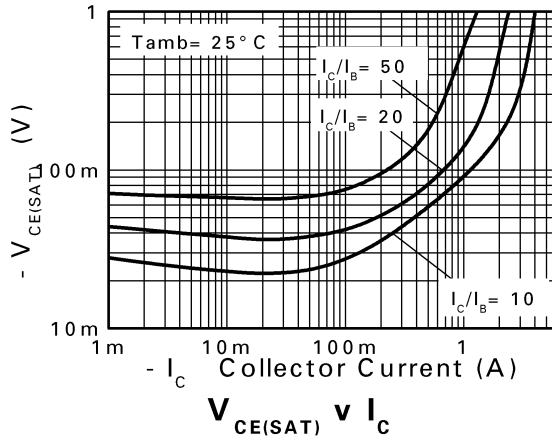


Electrical Characteristics (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

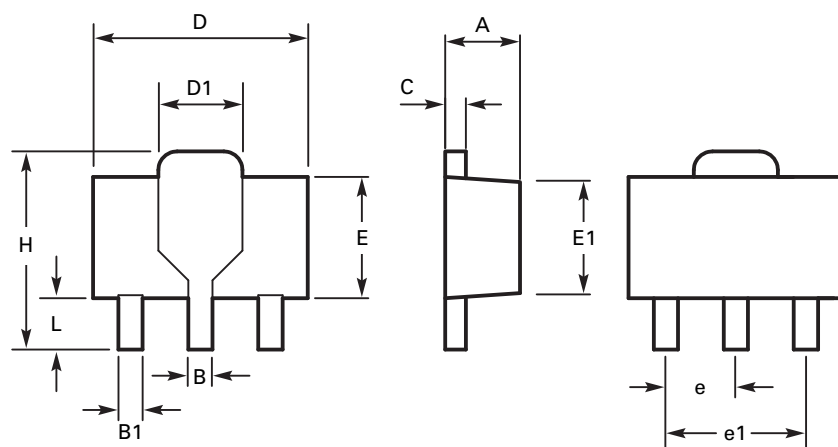
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Collector-Base breakdown voltage	BV_{CBO}	-180	-200		V	$I_C = -100\mu\text{A}$
Collector-Emitter breakdown voltage	BV_{CER}	-180	-200		V	$I_C = -100\mu\text{A}$, $R_B < 1\text{k}\Omega$
Collector-Emitter breakdown voltage	BV_{CEO}	-140	-160		V	$I_C = -10\text{mA}$ (*)
Emitter-Base breakdown voltage	BV_{EBO}	-7.0	-8.0		V	$I_E = -100\mu\text{A}$
Collector cut-off current	I_{CBO}		<1	-20 -0.5	nA μA	$V_{CB} = -150\text{V}$ $V_{CB} = -150\text{V}$, $T_{amb} = 100^{\circ}\text{C}$
Collector cut-off current	I_{CER} $R < 1\text{k}\Omega$		<1	-20 -0.5	nA μA	$V_{CB} = -150\text{V}$ $V_{CB} = -150\text{V}$, $T_{amb} = 100^{\circ}\text{C}$
Emitter cut-off current	I_{EBO}		<1	-10	nA	$V_{EB} = -6\text{V}$
Collector-Emitter saturation voltage	$V_{CE(sat)}$		-37	-60	mV	$I_C = -0.1\text{A}$, $I_B = -5\text{mA}$ (*)
			-50	-75	mV	$I_C = -0.5\text{A}$, $I_B = -50\text{mA}$ (*)
			-80	-115	mV	$I_C = -1\text{A}$, $I_B = -100\text{mA}$ (*)
			-255	-330	mV	$I_C = -3\text{A}$, $I_B = -300\text{mA}$ (*)
Base-emitter saturation voltage	$V_{BE(sat)}$		-910	-1010	mV	$I_C = -3\text{A}$, $I_B = -300\text{mA}$ (*)
Base-emitter turn-on voltage	$V_{BE(on)}$		-800	-900	mV	$I_C = -3\text{A}$, $V_{CE} = -5\text{V}$ (*)
Static forward current transfer ratio	h_{FE}	100	225			$I_C = -10\text{mA}$, $V_{CE} = -5\text{V}$ (*)
		100	200	300		$I_C = -1\text{A}$, $V_{CE} = -5\text{V}$ (*)
		45	100			$I_C = -3\text{A}$, $V_{CE} = -5\text{V}$ (*)
			5			$I_C = -10\text{A}$, $V_{CE} = -5\text{V}$ (*)
Transition frequency	f_T		120		MHz	$I_C = -100\text{mA}$, $V_{CE} = -10\text{V}$ $f = 50\text{MHz}$
Output capacitance	C_{OBO}		33		pF	$V_{CB} = -10\text{V}$, $f = 1\text{MHz}$ (*)
Switching times	t_{on}		42		ns	$I_C = -1\text{A}$, $V_{CC} = -50\text{V}$,
	t_{off}		636		ns	$I_{B1} = -I_{B2} = -100\text{mA}$

NOTES:(*) Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

Typical characteristics



Package Outline



DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
A	1.40	1.60	0.550	0.630	e	1.40	1.50	0.055	0.059
b	0.38	0.48	0.015	0.019	E	3.75	4.25	0.150	0.167
b1	-	0.53	-	0.021	E1	-	2.60	-	0.102
b2	1.50	1.80	0.060	0.071	G	2.90	3.00	0.114	0.118
c	0.28	0.44	0.011	0.017	H	2.60	2.85	0.102	0.112
D	4.40	4.60	0.173	0.181	-	-	-	-	-

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